CLAIMS

[Claim 1]

A semiconductor processing sheet comprising an adhesive layer on a base material, wherein

the adhesive layer comprises an adhesive resin (i) and a crosslinking agent (ii),

a content of the crosslinking agent (ii) in the adhesive layer is 10 to 50 parts by mass with respect to 100 parts by mass of the adhesive resin (i), and

the semiconductor processing sheet has a following characteristics:

when a thickness of the adhesive layer is 200 μm, a storage elastic modulus of the adhesive layer having a thickness of 200 μm at 0°C is equal to or less than 1,000 MPa; and

when the semiconductor processing sheet is adhered to a mirror surface of a semiconductor wafer, an adhesive force of the adhesive layer with respect to the mirror surface is equal to or less than 200 mN / 25 mm.

[Claim 2]

A semiconductor processing sheet comprising one adhesive layer on a base material, wherein

the semiconductor processing sheet has a following characteristics:

when a thickness of the adhesive layer is 200 μm, a storage elastic modulus of the adhesive layer having a thickness of 200 μm at 0°C is equal to or less than 1,000 MPa; and

when the semiconductor processing sheet is adhered to a mirror surface of a semiconductor wafer, an adhesive force of the adhesive layer with respect to the mirror

surface is equal to or less than 200 mN / 25 mm.

[Claim 3]

The semiconductor processing sheet according to Claim 1 or 2, wherein the adhesive layer is non-energy ray-curable.

[Claim 4]

The semiconductor processing sheet according to any one of Claims 1 to 3, further comprising a film adhesive on the adhesive layer.